

In the Claims:

Please cancel claims 1-27. Following is a complete listing of the claims pending in the application, as amended:

1-27. (Canceled)

28. (currently amended) A system for processing packaged microelectronic components, comprising:

a first loading station adapted to receive a first magazine containing a plurality of packaged microelectronic components, at least one of which includes at least one die;

a heating apparatus adapted to heat the packaged microelectronic components to a reflow temperature of a selected solder, the first loading station being adapted to transfer the packaged microelectronic components out of the first magazine and to the heating apparatus;

a solder plating apparatus adapted to receive the packaged microelectronic components from the heating system, the solder plating apparatus being adapted to deposit the selected solder on contacts of the packaged microelectronic components; and

a second loading station adapted to transfer the packaged microelectronic components from the solder plating apparatus to a second magazine.

29. (original) The system of claim 28 wherein the heating apparatus comprises a heating zone adapted to heat the packaged microelectronic components at a rate of at least about 5°C/second.

30. (original) The system of claim 28 wherein the heating apparatus comprises a heating zone adapted to heat the packaged microelectronic components at a rate of at least about 8°C/second.

31. (original) The system of claim 28 wherein the heating apparatus comprises a heating zone maintained at a temperature of at least about 350°C.

32. (original) The system of claim 28 wherein the heating apparatus comprises a heating zone and a cooling zone, the cooling zone being disposed between the heating zone and the solder plating apparatus.

33. (original) The system of claim 28 wherein the heating apparatus comprises an oven chamber and a transport system adapted to transport the packaged microelectronic components single-file through the oven chamber.

34. (currently amended) A system for processing microelectronic components, comprising:

- a cure station adapted to receive a first magazine carrying plurality of microelectronic components, ~~each—at least one of~~ which includes a curable encapsulant and at least one die, the cure station being adapted to cure the curable encapsulant by heating the microelectronic components to an encapsulant cure temperature in the first magazine;
- a pre-solder heating apparatus adapted to heat the packaged microelectronic components to a reflow temperature of a selected solder, the reflow temperature being greater than the encapsulant cure temperature;
- a first transport adapted to ~~transport the magazine of cured microelectronic components from the cure station to the pre-solder heating apparatus and~~ transfer the cured microelectronic components out of the first magazine and to the pre-solder heating apparatus;
- a solder plating apparatus adapted to receive the microelectronic components from the pre-solder heating apparatus, the solder plating apparatus being adapted to deposit the selected solder on contacts of the microelectronic components;

- a testing system adapted to test performance of the solder-bearing microelectronic components; and
- a second transport adapted to transfer the microelectronic components from the solder plating apparatus to a second magazine and transport the second magazine for further processing.

35. (original) The system of claim 34 wherein the pre-solder heating apparatus comprises a heating zone adapted to heat the microelectronic components at a rate of at least about 5°C/second.

36. (original) The system of claim 34 wherein the pre-solder heating apparatus comprises a heating zone adapted to heat the microelectronic components at a rate of at least about 8°C/second.

37. (original) The system of claim 34 wherein the pre-solder heating apparatus comprises a heating zone maintained at a temperature of at least about 350°C.

38. (original) The system of claim 34 wherein the pre-solder heating apparatus comprises a heating zone and a cooling zone, the cooling zone being disposed between the heating zone and the solder plating apparatus.

39. (original) The system of claim 34 wherein the pre-solder heating apparatus comprises an oven chamber and a transport system adapted to transport the microelectronic components single-file through the oven chamber.

40. (new) A system for processing packaged microelectronic components, comprising:

- a heating apparatus adapted to heat a packaged microelectronic component at a rate of at least about 5°C/second to a reflow temperature of a selected solder;
- a solder plating apparatus adapted to receive the packaged microelectronic components from the heating system and to deposit the selected solder on contacts of the packaged microelectronic components after the heated packaged microelectronic component has cooled to a temperature below the reflow temperature; and
- a testing system operatively associated with the solder plating apparatus and adapted to test performance of the solder-bearing microelectronic component, wherein the testing system is adapted to reject the packaged microelectronic component as defective if it fails to meet minimum performance criteria in the performance testing.

41. (new) The system of claim 40 wherein the heating apparatus comprises a heating zone adapted to heat the packaged microelectronic component at a rate of at least about 8°C/second.

42. (new) The system of claim 40 wherein the heating apparatus comprises a heating zone maintained at a temperature of at least about 350°C.

43. (new) The system of claim 40 wherein the heating apparatus comprises a heating zone and a cooling zone, the cooling zone being disposed between the heating zone and the solder plating apparatus.

44. (new) The system of claim 40 wherein the heating apparatus comprises an oven chamber and a transport system adapted to transport a plurality of packaged microelectronic components single-file through the oven chamber.

45. (new) The system of claim 40 further comprising a solder reflow heater, wherein the solder reflow heater is adapted to heat the solder-bearing microelectronic component at a rate that is no greater than the rate at which the heating apparatus is adapted to heat the packaged microelectronic component

46. (new) The system of claim 40 wherein the testing system includes a heater adapted to heat the packaged microelectronic component to an elevated temperature that is below 150°C.